Fabrication Notes:
1. Overall board height 53mil.
2. 20mil polish on inner plane.
3. Test all vias under BGA (Top Side only)
4. 1.2 oz copper on top and bottom
5. 1.0 oz copper on internal signal, power and ground layers

Design Notes:
1. Unless otherwise stated all dimensions are in mils

Layer Description:
- TOP LAYER
- BOTTOM LAYER
- MULT-LAYER HOLES
- MECHANICAL LAYERS